

Declaration for Patent Application

Docket Number: 1875.0230000

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled **High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascene Interconnect Process**, the specification of which is attached hereto unless the following box is checked:

☐ was filed on _____;
as United States Application Number or PCT International Application Number _____; and
was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information that is material to patentability as defined in 37 C.F.R. § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT international application, which designated at least one country other than the United States listed below, and have also identified below any foreign application for patent or inventor's certificate, or PCT international application having a filing date before that of the application on which priority is claimed.

Prior Foreign Application(s)	Priority Claimed
_____ (Application No.)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Country)	
_____ (Day Month Year Filed)	
_____ (Application No.)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Country)	
_____ (Day Month Year Filed)	

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) listed below.

_____ (Application No.)	_____ (Filing Date)
_____ (Application No.)	_____ (Filing Date)

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or under § 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information that is material to patentability as defined in 37 C.F.R. § 1.56 that became available between the filing date of the prior application and the national or PCT international filing date of this application.

_____ (Application No.)	_____ (Filing Date)	_____ (Status - patented, pending, abandoned)
_____ (Application No.)	_____ (Filing Date)	_____ (Status - patented, pending, abandoned)

Appl. No.: To Be Assigned
Docket No.: 1875.0230000

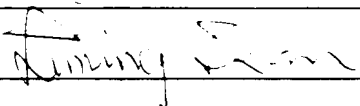
Send Correspondence to:

STERNE, KESSLER, GOLDSTEIN & FOX P.L.L.C.
1100 New York Avenue, N.W.
Suite 600
Washington, D.C. 20005-3934

Direct Telephone Calls to:

(202) 371-2600

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor	Liming Tsau	
Signature of sole or first inventor		Date 12/3/2000
Residence	Irvine, California	
Citizenship	Taiwan, ROC	
Mailing Address	14591 Fir Avenue	
	Irvine, California 92606	
Full name of second inventor		
Signature of second inventor		Date
Residence		
Citizenship		
Mailing Address		
Full name of third inventor		
Signature of third inventor		Date
Residence		
Citizenship		
Mailing Address		

USPS Form 1001 (Rev. 10-1999)

(Supply similar information and signature for subsequent joint inventors, if any.)